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(54) **ORGANIC LIGHT EMITTING DIODE
DISPLAY AND METHOD FOR
MANUFACTURING THE SAME**

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USPC **313/512; 313/504; 313/292**

(58) **Field of Classification Search** None
See application file for complete search history.

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(57) **ABSTRACT**

An organic light emitting diode (OLED) display is disclosed. In one embodiment, the display includes i) a substrate, ii) a driving circuit formed on the substrate, iii) an organic light emitting diode formed on the substrate and electrically connected to the driving circuit, iv) an encapsulation thin film formed on the driving circuit and organic light emitting diode and v) a spacer formed on the substrate and surrounding the encapsulation thin film.

11 Claims, 4 Drawing Sheets

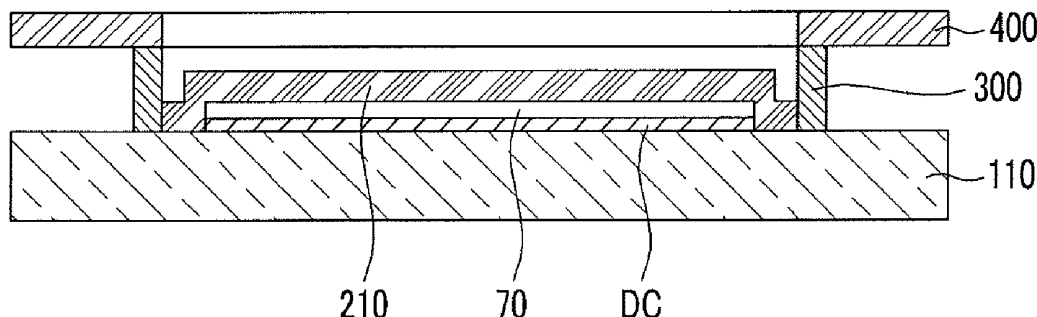


FIG. 1

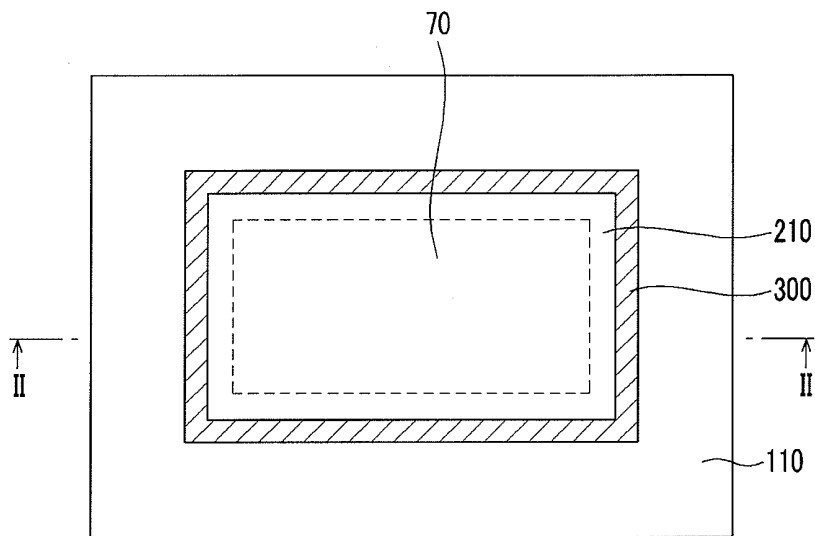


FIG. 2

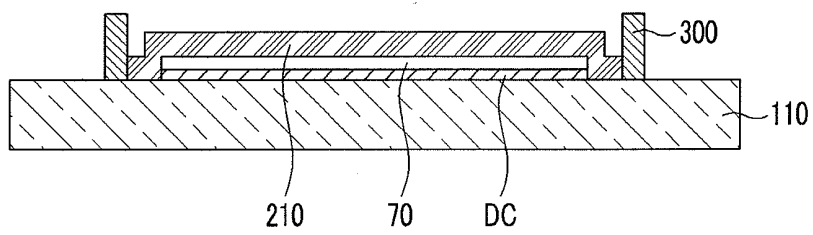


FIG. 3

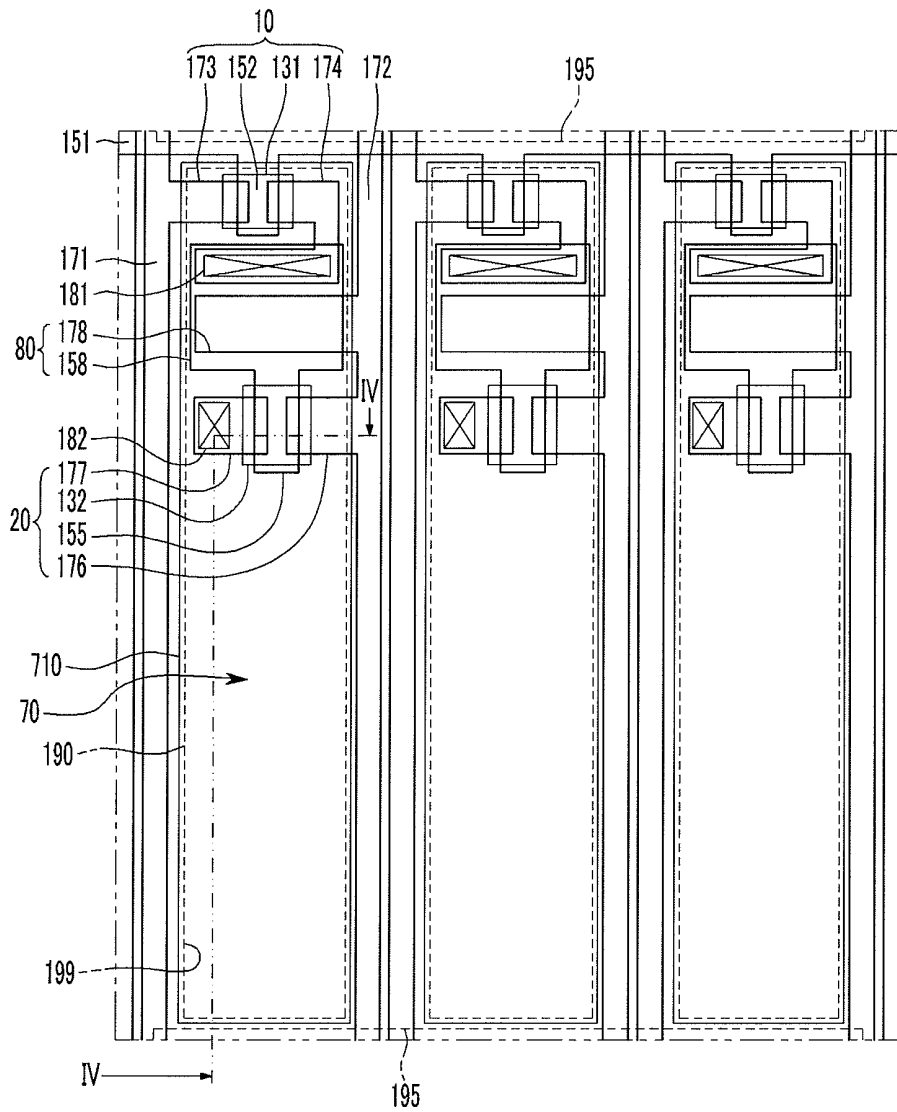


FIG. 4

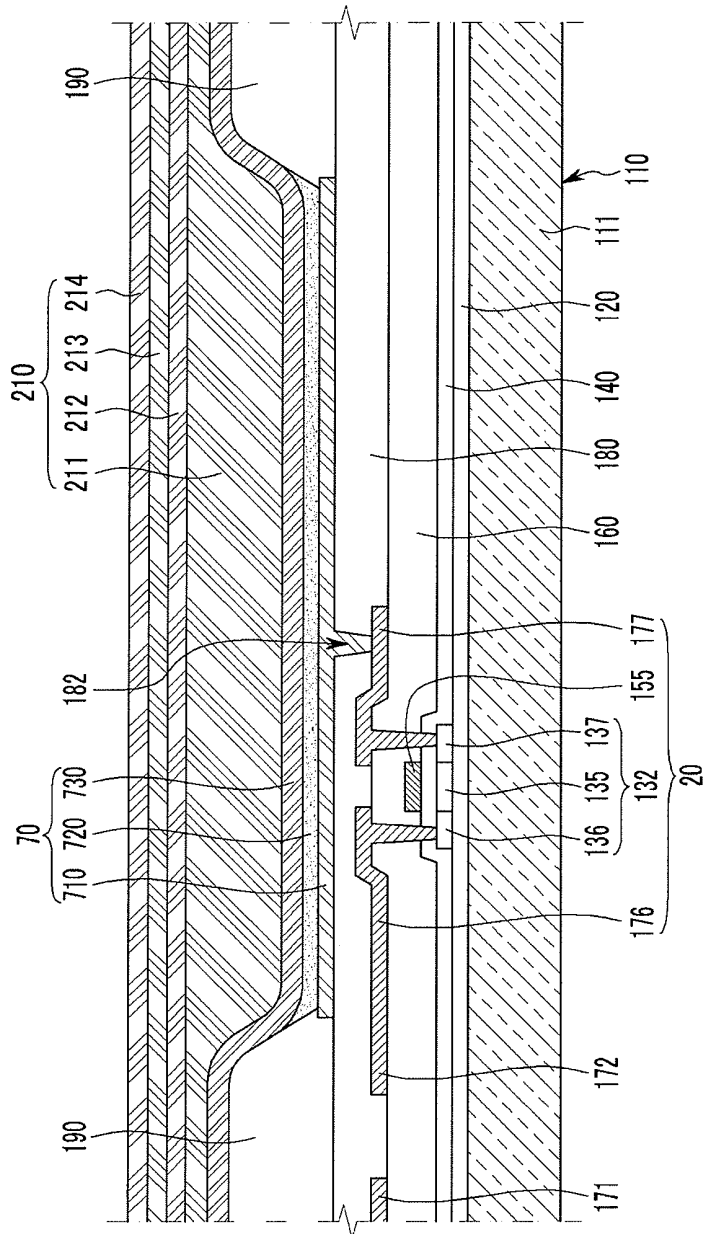
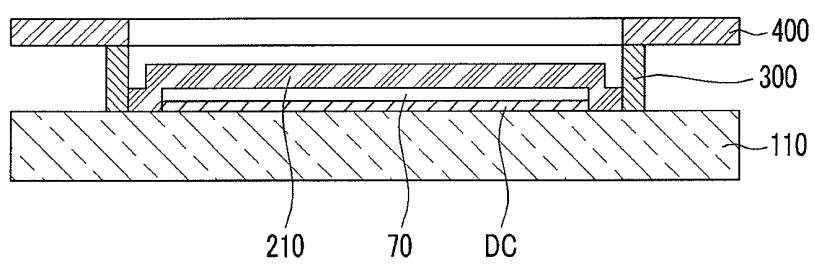


FIG. 5



**ORGANIC LIGHT EMITTING DIODE
DISPLAY AND METHOD FOR
MANUFACTURING THE SAME**

RELATED APPLICATIONS

This application claims priority to and the benefit of Korean Patent Application No. 10-2010-0050488 filed in the Korean Intellectual Property Office on May 28, 2010, the entire contents of which are incorporated herein by reference.

BACKGROUND

1. Field

The described technology generally relates to an organic light emitting diode (OLED) display, and more particularly, to an OLED display that has an encapsulation thin film and a manufacturing method thereof.

2. Description of the Related Technology

OLED displays are generally lightweight and have a thin profile. In addition, they are self-emissive and thus they do not require a separate light source. Furthermore, since the displays have characteristics of low power consumption, high luminance and high reaction speed, they have received much attention as the next generation display.

An OLED display includes a substrate on which an organic light emitting diode is formed. If moisture and oxygen penetrates into the organic light emitting diode that is made of an organic material, its performance degrades. Accordingly, an encapsulation method is generally used in order to prevent penetration of moisture and oxygen into OLED displays.

SUMMARY

One inventive aspect is an organic light emitting diode (OLED) display that suppresses performance degradation of an organic light emitting diode by internal penetration of moisture and oxygen.

Another aspect is a method for manufacturing an organic light emitting diode (OLED) display that suppresses the occurrence of particles.

Another aspect is an organic light emitting diode (OLED) display which includes: a substrate; a driving circuit and organic light emitting diode that is formed on the substrate; an encapsulation thin film that is formed on the driving circuit and organic light emitting diode; and a spacer that surrounds the encapsulation thin film on the substrate.

The height of the spacer may be higher than the height of the layered structure of the driving circuit and the organic light emitting diode.

The height of the spacer may be higher than the height of the layered structure of the driving circuit and the organic light emitting diode and the encapsulation thin film.

The height of the spacer may be 3 μm to 5 μm .

The spacer may include any one of acryl, urethane and polyimide (PI).

The spacer may be directly contacted with the encapsulation thin film along the circumference of the encapsulation thin film.

The encapsulation thin film may include at least a pair of inorganic film and organic film, and may be formed by alternately layering the inorganic film and the organic film.

Another aspect is a method for manufacturing an organic light emitting diode (OLED) display, which includes: preparing a substrate; forming a spacer on the substrate along an edge of the substrate; forming a driving circuit and organic light emitting diode on the substrate in an internal area that is

partitioned by the spacer; and forming an encapsulation thin film so as to cover the driving circuit and the organic light emitting diode. The mask that is used in the forming of the driving circuit and the organic light emitting diode may be disposed on the spacer.

The height of the spacer may be higher than the height of the layered structure of the driving circuit and the organic light emitting diode.

The height of the spacer may be higher than the height of the layered structure of the driving circuit and the organic light emitting diode and the encapsulation thin film.

The height of the spacer may be 3 μm to 5 μm .

The spacer may be formed by including any one of acryl, urethane and polyimide (PI).

The encapsulation thin film may be contacted with the spacer in the internal area.

The encapsulation thin film may be formed by alternately layering at least a pair of inorganic film and organic film. Another aspect is an organic light emitting diode (OLED) display, comprising: a substrate; a driving circuit formed on the substrate; an organic light emitting diode formed on the substrate and electrically connected to the driving circuit; an encapsulation thin film formed on the driving circuit and organic light emitting diode; and a spacer formed on the substrate and surrounding the encapsulation thin film.

In the above display, the height of the spacer is greater than the height of the layered structure of the driving circuit and the organic light emitting diode. In the above display, the height of the spacer is greater than the height of the layered structure of i) the driving circuit, ii) the organic light emitting diode and iii) the encapsulation thin film. In the above display, the height of the spacer is about 3 μm to about 5 μm .

In the above display, the spacer is formed at least partially of acryl, urethane and polyimide (PI). In the above display, the spacer directly contacts the encapsulation thin film along the circumference of the encapsulation thin film. In the above display, the encapsulation thin film includes at least a pair of an inorganic film and an organic film which are alternately formed.

Another aspect is a method of manufacturing an organic light emitting diode (OLED) display, comprising: preparing a substrate; forming a spacer on the substrate along an edge of the substrate; forming a driving circuit and an organic light emitting diode on the substrate to be surrounded by the spacer; and forming an encapsulation thin film so as to substantially cover the driving circuit and the organic light emitting diode, wherein the mask that is used in the forming of the driving circuit and the organic light emitting diode is supported by and contacts the spacer.

In the above method, the height of the spacer is greater than the height of the layered structure of the driving circuit and the organic light emitting diode. In the above method, the height of the spacer is greater than the height of the layered structure of i) the driving circuit, ii) the organic light emitting diode and iii) the encapsulation thin film. In the above method, the height of the spacer is about 3 μm to about 5 μm . In the above method, the spacer is formed at least partially of acryl, urethane and polyimide (PI).

In the above method, the encapsulation thin film contacts the spacer. In the above method, the encapsulation thin film is formed by alternately layering at least a pair of an inorganic film and an organic film. In the above method, the spacer substantially completely surrounds the encapsulation thin film in a selected plane:

Another aspect is an organic light emitting diode (OLED) display, comprising: a substrate; an organic light emitting diode formed on a surface of the substrate; an encapsulation

layer covering the organic light emitting diode, wherein at least part of the encapsulation layer contacts the surface of the substrate; and a spacer formed on the surface of the substrate and surrounding the encapsulation layer.

In the above display, the spacer contacts the encapsulation layer: In the above display, the spacer substantially completely surrounds the encapsulation layer in a selected plane: In the above display, the spacer is greater in height than the encapsulation layer, and wherein the height is defined from the surface of the substrate. In the above display, the height of the spacer is about 3 μm to about 5 μm .

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a top plan view of an organic light emitting diode (OLED) display according to an embodiment.

FIG. 2 is a cross-sectional view of an organic light emitting diode (OLED) display according to an embodiment, which is taken along the line II-II of FIG. 1.

FIG. 3 is a plan layout view of a pixel of an organic light emitting diode (OLED) display according to an embodiment.

FIG. 4 is a cross-sectional view of a pixel of an organic light emitting diode (OLED) display according to an embodiment, which is taken along the line IV-IV of FIG. 3.

FIG. 5 is a view that illustrates a contact of an organic light emitting diode (OLED) display and a mask according to an embodiment.

DETAILED DESCRIPTION

In general, the substrate for an OLED display is encapsulated by using metal or glass. However, if glass is used, there is a lower limit as to by how much the thickness of the entire display device can be reduced. In addition, flexible OLED displays are possible, and in view of the hardness of metal and glass, they are not suitable for such designs.

In manufacturing OLED displays, a mask is generally used to pattern OLED elements such as an organic light emitting diode and a driving circuit for supplying electrical signals to it. The mask may contact the substrate in the patterning process and particles may be introduced by the contact. The particles penetrate into the OLED display in conjunction with moisture and oxygen causing a deleterious effect to the organic light emitting diode, such that the life-span of the OLED display is reduced.

Hereinafter, embodiments will be described more fully hereinafter with reference to the accompanying drawings.

The drawings and description are to be regarded as illustrative in nature and not restrictive, and the size and thickness of each component shown in the drawings are arbitrarily shown for understanding and ease of description. In addition, it will be understood that when an element such as a layer, film is referred to as being "on" another element, it can be directly on the other element or intervening elements may also be present.

Referring to FIGS. 1 and 2, an OLED display includes a display substrate 110, an encapsulation thin film 210 and spacer 300.

The display substrate 110 is configured to display an image, a driving circuit (DC) is formed on the display substrate 110, an organic light emitting diode 70 is formed on the driving circuit (DC), thus implementing the image through it. The organic light emitting diode 70 includes the organic emission layer that is made of an organic material, and is driven by a driving circuit (DC) that includes a thin film transistor and a capacitor, thus emitting light.

The encapsulation thin film 210 is formed on the organic light emitting diode 70, thus sealing the organic light emitting diode 70. The encapsulation thin film 210 is formed so that the organic film and the inorganic film are alternately layered on the organic light emitting diode 70 to cover the organic light emitting diode 70 and driving circuit (DC).

In one embodiment, the OLED display requires a low water vapor transmission rate (WVTR) in order to ensure a sufficient life-span. In one embodiment, by sealing the organic light emitting diode 70 using the encapsulation thin film 210, it suppresses the penetration of moisture and oxygen into the organic light emitting diode 70 and driving circuit (DC), thereby implementing the low water vapor transmission rate of about 10^{-6} $\text{g}/\text{m}^2/\text{day}$ or less.

In one embodiment, the spacer 300 surrounds the circumference of the encapsulation thin film 210 on the display substrate 110. The spacer 300 is configured to support the mask in order to form the driving circuit (DC) and organic light emitting diode 70, and will be described later.

In one embodiment, the plane shape of the spacer 300 is determined according to the plane shape of the organic light emitting diode 70 and the encapsulation thin film 210. In one embodiment, since the plane shape of the organic light emitting diode 70 and the encapsulation thin film 210 is a substantially rectangular shape, the spacer 300 that surrounds the encapsulation thin film 210 has a substantially rectangular band plane shape. In one embodiment, the encapsulation thin film 210 contacts the spacer 300. That is, the encapsulation thin film 210 contacts the spacer 300, and is formed in substantially the entire area on the display substrate 110 that is partitioned by the spacer 300.

In one embodiment, the height of the spacer 300 is greater than the height of the layered structure of the driving circuit (DC) and the organic light emitting diode 70. The height of the spacer 300 may be greater than the height of the layered structure of driving circuit (DC), organic light emitting diode 70 and encapsulation thin film 210. The height of the spacer may be about 3 μm to about 5 μm , but in the case of when the height of the encapsulation thin film 210 is lower than about 3 μm , the height of the spacer may be lower than about 3 μm .

The spacer 300 may be formed of the same material as the pixel definition film that will be described later. For example, the spacer 300 may be formed of an organic material such as acryl, urethane, and polyimide (PI). As described above, in the case of when the spacer 300 is formed of the same material as the pixel definition film, while the pixel definition film is formed, the spacer 300 is formed at the same time, such that a whole process may be simplified. However, the material of the above spacer is illustrated, various modifications may be possible by those who are skilled in the art.

As described above, it is possible to more efficiently suppress the penetration of moisture and oxygen into by forming the spacer 300 that surrounds the circumference of the encapsulation thin film 210. In addition, in the manufacturing process, it is possible to lower the occurrence of defects and prolong a life-span of the OLED display by suppressing the occurrence of particles, and this will be described later.

Referring to FIG. 3 and FIG. 4, an active matrix (AM) type organic light emitting diode (OLED) display that has a 2Tr-1 Cap structure which includes two thin film transistors (TFT), and one capacitor for one pixel is shown, but is not considered limiting. For example, the OLED display may be provided with three or more thin film transistors and two or more capacitors for one pixel, and a disposition of the wire may be changed to provide various structures. Here, the pixel means a minimum unit that displays an image, and the OLED display displays an image through a plurality of pixels.

The display substrate **110** includes a switching thin film transistor **10**, a driving thin film transistor **20**, a capacitor **80** and an organic light emitting diode (OLED) **70** for each one pixel. In addition, the display substrate **110** further includes a gate line **151** that is disposed along a predetermined direction, and a data line **171** and a common electric power line **172** that insulately cross the gate line **151**.

The organic light emitting diode **70** includes the first electrode **710**, the organic emission layer **720** that is formed on the first electrode **710**, and the second electrode **730** that is formed on the first organic emission layer **720**. In one embodiment, the pixel electrode **710** is an anode that is a hole injection electrode and the common electrode **730** is a cathode that is an electron injection electrode. The holes and electrons are injected from the pixel electrode **710** and common electrode **730** to the organic emission layer **720**, and when the exciton that is combined with the injected hole and electron falls from the excited state to the bottom state, light emission is implemented.

The capacitor **80** includes the first capacitor plate **158** and the second capacitor plate **178** that are disposed between gate insulating layers **140** that act as a dielectric material. The capacitor capacitance is determined by the charge that is accumulated in the capacitor **80** and the voltage between both capacitor plates **158** and **178**.

The switching thin film transistor **10** includes a switching semiconductor layer **131**, switching gate electrode **152**, a switching source electrode **173** and a switching drain electrode **174**. The driving thin film transistor **20** includes a driving semiconductor layer **132**, a driving gate electrode **155**, a driving source electrode **176** and a driving drain electrode **177**. The switching thin film transistor **10** is a switching element that selects the pixel that emits light. The switching gate electrode **152** is electrically connected to the gate line **151**, the switching source electrode **173** is electrically connected to the data line **171**, and the switching drain electrode **174** is separated from the switching source electrode **173** and connected to the first capacitor plate **158**.

The driving thin film transistor **20** applies a driving power for emitting light of the organic emission layer **720** of the organic light emitting diode **70** to the pixel electrode **710** in the selected pixel. The driving gate electrode **155** is electrically connected to the first capacitor plate **158**, the source electrode **176** and the second capacitor plate **178** are electrically connected to the common power line **172**, and the driving drain electrode **177** is electrically connected to the pixel electrode **710** of the organic light emitting diode **70** through a contact hole **182**.

By the above structure, the switching thin film transistor **10** is operated by the gate voltage that is applied to the gate line **151** and transfers the data voltage that is applied to the data line **171** to the driving thin film transistor **20**. The voltage that corresponds to a difference in the common voltage that is applied from the common power line **172** to the driving thin film transistor **20** and the data voltage that is transferred from the switching thin film transistor **10** is stored in the capacitor **80**. Further, the current that corresponds to the voltage that is stored in the capacitor **80** flows through the driving thin film transistor **20** to the organic light emitting diode **70** to allow the organic light emitting diode **70** to emit light.

Referring to FIG. 4, a method of manufacturing an OLED display according to one embodiment will be described.

In one embodiment, the substrate member **111** of the display substrate **110** is formed of an insulating substrate such as glass and the like, and the buffer layer **120** is formed on the first substrate member **111**. The buffer layer **120** may be formed of silicon nitride (SiNx), silicon oxide (SiOx), silicon

nitride (SiOxNy) and the like, and the buffer layer **120** may be omitted according to the kind of substrate member **111** and the process condition. The driving semiconductor layer **132** is formed on the buffer layer **120**. The driving semiconductor layer **132** includes a channel region **135** in which an impurity is not doped, and a source region **136** and a drain region **137** that are p+ doped to both ends of the channel region **135**. In one embodiment, the doped ion material is a P type impurity such as boron (B).

In one embodiment, a thin film transistor that has a PMOS structure that uses the P type impurity as the driving thin film transistor **20** is used. Alternatively, a thin film transistor that has an NMOS structure or CMOS structure may be used. In addition, in one embodiment, the driving thin film transistor **20** is a polycrystalline thin film transistor that includes a polysilicon film, but the switching thin film transistor **10** not shown in FIG. 4 may be a polycrystalline thin film transistor or amorphous thin film transistor that includes an amorphous silicon film.

In one embodiment, the gate insulating layer **140** that is formed at least partially of silicon nitride or silicon oxide is formed on the driving semiconductor layer **132**. The gate wire that includes the gate electrode **155** is formed on the gate insulating layer **140**, and the gate wire further includes the gate line **151**, the first capacitor plate **158** and the other wires. In addition, the driving gate electrode **155** is formed so as to overlap with at least a portion of the driving semiconductor layer **132**, particularly the channel region **135**. On the gate insulating layer **140**, the interlayer insulating layer **160** that covers the driving gate electrode **155** is formed. The gate insulating layer **140** and the interlayer insulating layer **160** have holes that expose the source region **136** and drain region **137** of the driving semiconductor layer **132**. In one embodiment, the interlayer insulating layer **160** is formed at least partially of silicon nitride, silicon oxide and the like likewise the gate insulating layer **140**. The data wire that includes the driving source electrode **176** and driving drain electrode **177** is formed on the interlayer insulating layer **160**, and the data wire further includes the data line **171**, the common power line **172**, the second capacitor plate **178** and the other wires. In addition, the driving source electrode **176** and driving drain electrode **177** are electrically connected to the source region **136** and drain region **137** of the driving semiconductor layer **132** through the holes that are formed on the interlayer insulating layer **160** and gate insulating layer **140**.

As described above, the driving semiconductor layer **132**, driving gate electrode **155**, driving source electrode **176** and driving drain electrode **177** are formed, and the configuration of the driving thin film transistor **20** is not limited to the above examples but may be variously modified by those who are skilled in the art.

A planarization layer **180** that covers a data wire is formed on the interlayer insulating layer **160**, and the contact hole **182** that exposes a portion of the drain electrode **177** is formed on the planarization layer **180**. Meanwhile, any one of the interlayer insulating layer **160** and planarization layer **180** may be omitted.

The pixel electrode **710** of the organic light emitting diode **70** is formed on the planarization layer **180**, and the pixel electrode **710** is electrically connected through the contact hole **182** to the drain electrode **177**. In addition, a pixel definition film **190** that has a plurality of openings **199** that expose each pixel electrode **710** is formed on the planarization layer **180**. The portion on which the pixel definition film **190** is formed substantially becomes a non-light emitting area and the portion on which the opening **199** of the pixel definition film **190** is formed substantially becomes a light emitting

area. The organic emission layer **720** is formed on the pixel electrode **710**, and the common electrode **730** is formed on the organic emission layer **720**, thereby constituting the organic light emitting diode **70**. The organic emission layer **720** is formed of a low molecular organic material or high molecular organic material, and the organic emission layer **720** may be formed of a multilayer that includes one or more of a hole injection layer (HIL), hole transport layer (HTL), electron transport layer (ETL) and electron injection layer (EIL).

An encapsulation thin film **210** for sealing the organic light emitting diode **70** is formed on the common electrode **730**. The encapsulation thin film **210** includes one pair or more of organic films **211** and **213** and inorganic films **212** and **214**, and is formed by alternately layering the organic films **211** and **213** and inorganic films **212** and **214**. In one embodiment, the encapsulation thin film **210** includes two pairs of organic films **211** and **213** and inorganic films **212** and **214**, but it is not limited thereto.

As described above, the encapsulation thin film **210** that is obtained by alternately layering the organic films **211** and **213** and the inorganic films **212** and **214** is formed on the organic light emitting diode **70**, such that the contacting of moisture or oxygen to the organic light emitting diode **70** is suppressed to prevent performance degradation.

Meanwhile, the switching thin film transistor **10**, the driving thin film transistor **20**, the capacitor **80** and the organic light emitting diode **70** are patterned by using the mask. In this patterning process, the mask contacts the display substrate **110** to generate particles. The particles penetrate into the OLED display to deteriorate the performance of the organic light emitting diode, and may be a cause of the occurrence of defects of the OLED display and life-span deterioration thereof. Accordingly, in one embodiment, as described above, the occurrence of defects of the OLED display and the life-span deterioration thereof are suppressed by forming the spacer **300** on the display substrate **110**.

FIG. 5 is a view that illustrates a contact of an OLED display and a mask according to an embodiment, and a manufacturing method of the OLED display will be described with reference to it.

In one embodiment, the OLED display is manufactured by preparing a display substrate **110**, forming a spacer **300** along an edge of the display substrate **110**, forming a driving circuit (DC) and organic light emitting diode **70**, and forming an encapsulation thin film **210** to cover the driving circuit (DC) and organic light emitting diode **70**. As shown in FIG. 5, the driving circuit (DC) and organic light emitting diode **70** are formed in an internal area of the areas that are partitioned by the spacer **300** on the display substrate **110**, and are formed through deposition and patterning processes using the mask **400**.

As described above, if the mask **400** contacts the display substrate **110**, the particles are generated and moisture and oxygen may easily penetrate into the OLED device, as a result, the performance of the OLED display may be deteriorated and defects may be generated. However, according to one embodiment, the spacer **300** is formed on the display substrate **110**, the mask **400** is disposed to be supported on the spacer **300**, thereby suppressing the above problems.

In one embodiment, since the driving circuit (DC) and organic light emitting diode **70** are formed by using the mask **400**, the height of the spacer **300** that supports the mask **400** is greater than the height of the layered structure of the driving circuit (DC) and organic light emitting diode **70**.

In addition, the height of the spacer **300** may be greater than the height of the layered structure of the driving circuit (DC),

organic light emitting diode **70** and encapsulation thin film **210**. In the area that is partitioned by the spacer **300**, the encapsulation thin film **210** is layered to cover the driving circuit (DC) and organic light emitting diode **70**. If the height of the spacer **300** is greater than the height of the layered structure of the driving circuit (DC), organic light emitting diode **70** and encapsulation thin film **210**, in the area that is partitioned by the spacer **300**, the process for layering the encapsulation thin film **210** may be easily performed.

In one embodiment, the encapsulation thin film **210** is formed by alternately layering at least a pair of inorganic film and organic film. In addition, since the encapsulation thin film **210** is layered in the area that is partitioned by the spacer **300** on the organic light emitting diode **70**, it may directly contact the spacer **300**. By this process, the organic light emitting diode **70** may be sealed by the encapsulation thin film **210** and an external boundary may be formed by the spacer **300**. Accordingly, it is possible to easily suppress the penetration of moisture and oxygen into the OLED display and to suppress the occurrence of particles in the process.

According to at least one of the disclosed embodiments, it is possible to prevent performance degradation of an organic light emitting diode (OLED) display by suppressing penetration of moisture and oxygen into the display.

In addition, in the process of manufacturing the OLED display, it is possible to suppress the occurrence of defects of the display and prolong life-span.

While this disclosure has been described in connection with certain embodiments, it is to be understood that the disclosed embodiments are not limiting. Thus, the appended claims are intended to cover various modifications and equivalent arrangements.

What is claimed is:

1. An organic light emitting diode (OLED) display, comprising:

- a substrate;
- a driving circuit formed on the substrate;
- an organic light emitting diode formed on the substrate and electrically connected to the driving circuit;
- an encapsulation thin film formed on the driving circuit and organic light emitting diode; and
- a spacer formed on the substrate and surrounding the encapsulation thin film, wherein the encapsulation thin film comprises a side surface facing the spacer, and wherein only part of the side surface of the encapsulation thin film contacts the spacer.

2. The display of claim 1, wherein the height of the spacer is greater than the height of the layered structure of the driving circuit and the organic light emitting diode.

3. The display of claim 2, wherein the height of the spacer is greater than the height of the layered structure of i) the driving circuit, ii) the organic light emitting diode and iii) the encapsulation thin film.

4. The display of claim 3, wherein the height of the spacer is about 3 to about 5 μm .

5. The display of claim 1, wherein the spacer is formed at least partially of acryl, urethane and polyimide (PI).

6. The display of claim 1, wherein the encapsulation thin film includes at least a pair of an inorganic film and an organic film which are alternately formed.

7. An organic light emitting diode (OLED) display, comprising:

- a substrate;
- an organic light emitting diode formed on a surface of the substrate;

an encapsulation layer covering the organic light emitting diode, wherein at least part of the encapsulation layer contacts the surface of the substrate; and

a spacer formed on the surface of the substrate and surrounding the encapsulation layer, wherein the encapsulation layer comprises a side surface facing the spacer, and wherein only part of the side surface of the encapsulation layer contacts the spacer. 5

8. The display of claim 7, wherein the spacer contacts the encapsulation layer. 10

9. The display of claim 7, wherein the spacer substantially completely surrounds the encapsulation layer in a selected plane.

10. The display of claim 7, wherein the spacer is greater in height than the encapsulation layer, and wherein the height is defined from the surface of the substrate. 15

11. The display of claim 7, wherein the height of the spacer is about 3 μm to about 5 μm .

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专利名称(译)	有机发光二极管显示器及其制造方法		
公开(公告)号	US8415882	公开(公告)日	2013-04-09
申请号	US13/049795	申请日	2011-03-16
[标]申请(专利权)人(译)	三星显示有限公司		
申请(专利权)人(译)	三星移动显示器有限公司.		
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摘要(译)

公开了一种有机发光二极管 (OLED) 显示器。在一个实施例中，显示器包括 i) 基板， ii) 形成在基板上的驱动电路， iii) 形成在基板上并电连接到驱动电路的有机发光二极管， iv) 形成在基板上的封装薄膜。驱动电路和有机发光二极管以及 v) 形成在基板上并围绕封装薄膜的间隔物。

